

HiPerFET™

Power MOSFETs

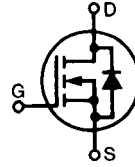
Q-Class

N-Channel Enhancement Mode
Avalanche Rated,
Low Q_g , High dv/dt

IXFH20N80Q
IXFK20N80Q
IXFT20N80Q

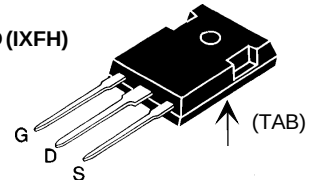
$V_{DSS} = 800 \text{ V}$
 $I_{D25} = 20 \text{ A}$
 $R_{DS(on)} = 0.42 \Omega$

$t_{rr} \leq 250 \text{ ns}$

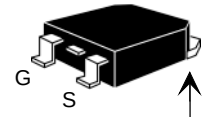


Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	800	V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1 \text{ M}\Omega$	800	V
V_{GS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	$T_C = 25^\circ\text{C}$	20	A
I_{DM}	$T_C = 25^\circ\text{C}$, pulse width limited by T_{JM}	80	A
I_{AR}	$T_C = 25^\circ\text{C}$	20	A
E_{AR}	$T_C = 25^\circ\text{C}$	45	mJ
E_{AS}	$T_C = 25^\circ\text{C}$	1.5	J
dv/dt	$I_S \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2 \Omega$	5	V/ns
P_D	$T_C = 25^\circ\text{C}$	360	W
T_J		-55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-55 ... +150	$^\circ\text{C}$
T_L	1.6 mm (0.063 in) from case for 10 s	300	$^\circ\text{C}$
M_d	Mounting torque	TO-247 TO-264	1.13/10 0.9/6 Nm/lb.in.
Weight		TO-247 TO-268 TO-264	6 4 10 g

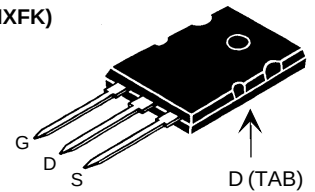
TO-247 AD (IXFH)



TO-268 (D3) (IXFT)



TO-264 AA (IXFK)



G = Gate
S = Source

TAB = Drain

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
V_{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	800		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4 \text{ mA}$	2.5		4.5 V
I_{GSS}	$V_{GS} = \pm 20 \text{ V}$, $V_{DS} = 0$			$\pm 200 \text{ nA}$
I_{DSS}	$V_{DS} = V_{DSS}$, $V_{GS} = 0 \text{ V}$			25 μA 1 mA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$, $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2 \%$			0.42 Ω

Features

- IXYS advanced low Q_g process
- International standard packages
- Epoxy meet UL 94V-0, flammability classification
- Low $R_{DS(on)}$ low Q_g
- Avalanche energy and current rated
- Fast intrinsic rectifier

Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
g_{fs}	$V_{DS} = 10\text{ V}$; $I_D = 0.5 \cdot I_{D25}$, pulse test	11	19	S
C_{iss}	$V_{GS} = 0\text{ V}$, $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$		5100	pF
C_{oss}			500	pF
C_{rss}			170	pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$ $R_G = 1.5\ \Omega$ (External),		28	ns
t_r			27	ns
$t_{d(off)}$			74	ns
t_f			14	ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$		150	nC
Q_{gs}			34	nC
Q_{gd}			80	nC
R_{thJC}			0.35	K/W
R_{thCK}	TO-247		0.25	K/W
	TO-264		0.15	K/W

Source-Drain Diode		Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
Symbol	Test Conditions	min.	typ.	max.
I_S	$V_{GS} = 0\text{ V}$			20 A
I_{SM}	Repetitive; pulse width limited by T_{JM}			80 A
V_{SD}	$I_F = I_S$, $V_{GS} = 0\text{ V}$, Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$			1.5 V
t_{rr}	$I_F = I_S$, $-di/dt = 100\text{ A}/\mu\text{s}$, $V_R = 100\text{ V}$		1	250 ns
Q_{RM}			9	μC
I_{RM}				A

TO-268AA (IXFT) (D³ PAK)

Technical drawing of the TO-268AA (IXFT) (D³ PAK) package showing three views: top, side, and front. The top view shows dimensions E (width), D (height), L1 (lead length), L2 (lead width), L3 (lead thickness), L4 (lead width), and mounting holes with diameter $\phi 2$ and spacing b. The side view shows dimensions A (height), A1 (height), C2 (height), H (height), and C (height). The front view shows dimensions E1 (width), D1 (height), and mounting holes with diameter $\phi 2$ and spacing b.

Technical drawing of the TO-268AA (IXFT) (D³ PAK) package showing a detail view of the mounting holes. The drawing shows the spacing between the mounting holes and the diameter of the holes.

Technical drawing of the TO-268AA (IXFT) (D³ PAK) package showing a detail view of the lead and mounting holes. The drawing shows the lead length L3, the lead thickness $\sigma \sim 8$, the lead width L, and the mounting hole diameter A2.

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.9	5.1	.193	.201
A ₁	2.7	2.9	.106	.114
A ₂	.02	.25	.001	.010
b	1.15	1.45	.045	.057
b ₂	1.9	2.1	.75	.83
C	.4	.65	.016	.026
D	13.80	14.00	.543	.551
E	15.85	16.05	.624	.632
E ₁	13.3	13.6	.524	.535
e	5.45 BSC		.215 BSC	
H	18.70	19.10	.736	.752
L	2.40	2.70	.094	.106
L1	1.20	1.40	.047	.055
L2	1.00	1.15	.039	.045
L3	0.25 BSC		.010 BSC	
L4	3.80	4.10	.150	.161